

LVDS Interface LSI

# 35bit LVDS Receiver 5:35 DeSerializer

## BU90R104

### ●General Description

The BU90R104 receiver operates from 8MHz to 112MHz wide clock range.

The BU90R104 converts the LVDS serial data streams back into 35bits of LVCMOS parallel data.

Data is transmitted seven times (7X) stream and reduce the cable number by 3(1/3) or less.

I/O Voltage range is 2.3 to 3.6V, so it is available for many products.

### ●Features

- 5 channels of LVDS data stream are converted to 35bits data of parallel LVCMOS level outputs.
- 30bits of RGB output data, 5bits of timing and control output data(HSYNC, VSYNC, DE, CTL1 and CTL2) are transmitted available.
- Support clock frequency from 8MHz up to 112MHz.
- Support consumer video format including 480i, 480P, 720P and 1080i as well.
- Support many kinds of PC video formats such as VGA, SVGA, XGA and SXGA.
- Provide 784Mbps per 1ch or 3.92Gbps per device throughput rate using 112MHz clock rate.

### ●Key Specifications

- Supply Voltage Range 2.30 to 3.60 V
- Operating Frequency 8 to 112 MHz
- Operating Temperature Range -40 to +85 °C

### ●Packages

- TQFP64V 12.0mm×12.0mm×1.0mm

### ●Applications

- Flat panel display
- Security camera, Digital camera
- Tablet
- User programmable LVCMOS data output triggering timing by using either rising or falling edge of clock.
- 30bit LVDS transmitter is recommended to use BU8254KVT.

•Block Diagram

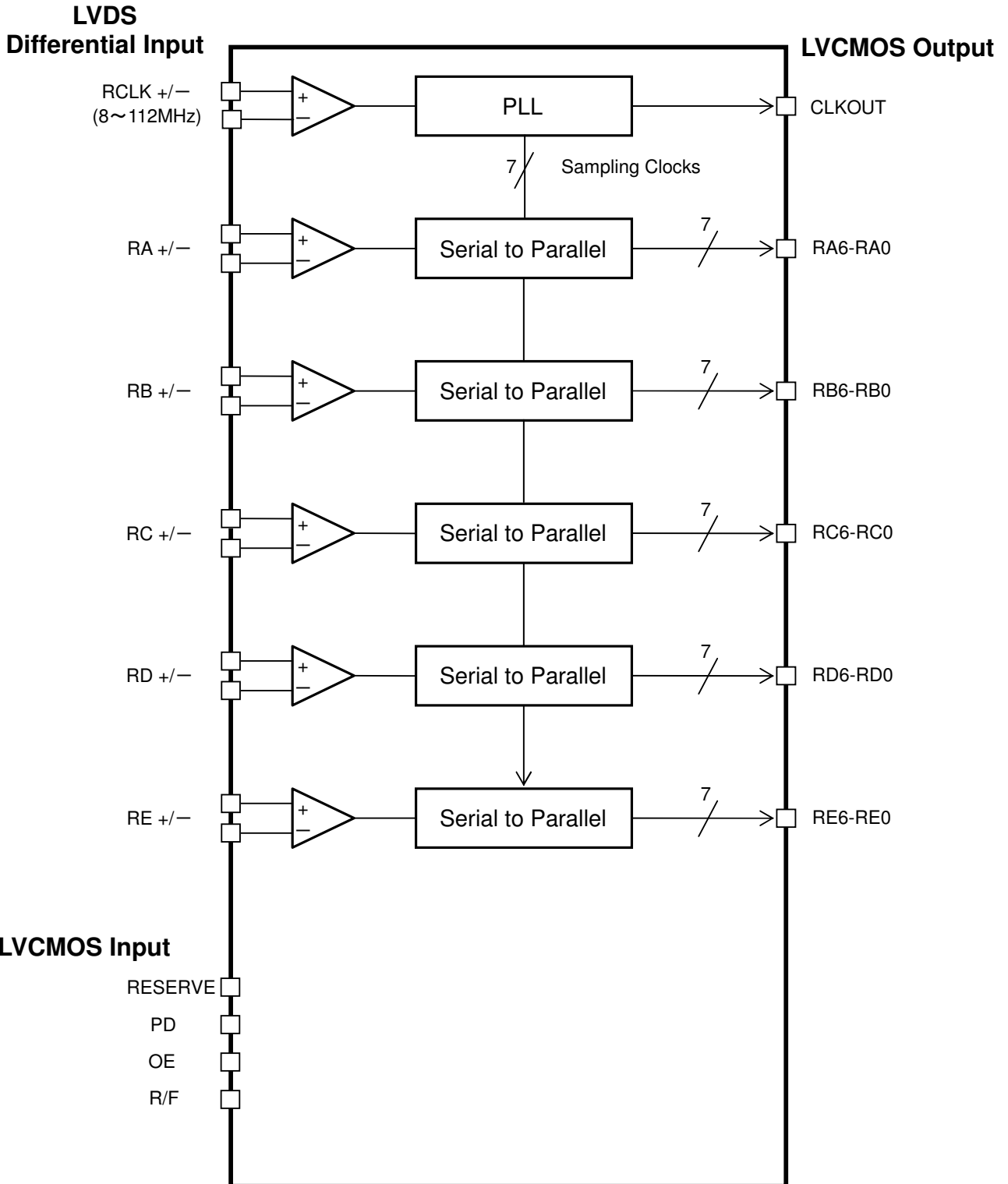


Figure 1. Block Diagram

●Pin Configuration

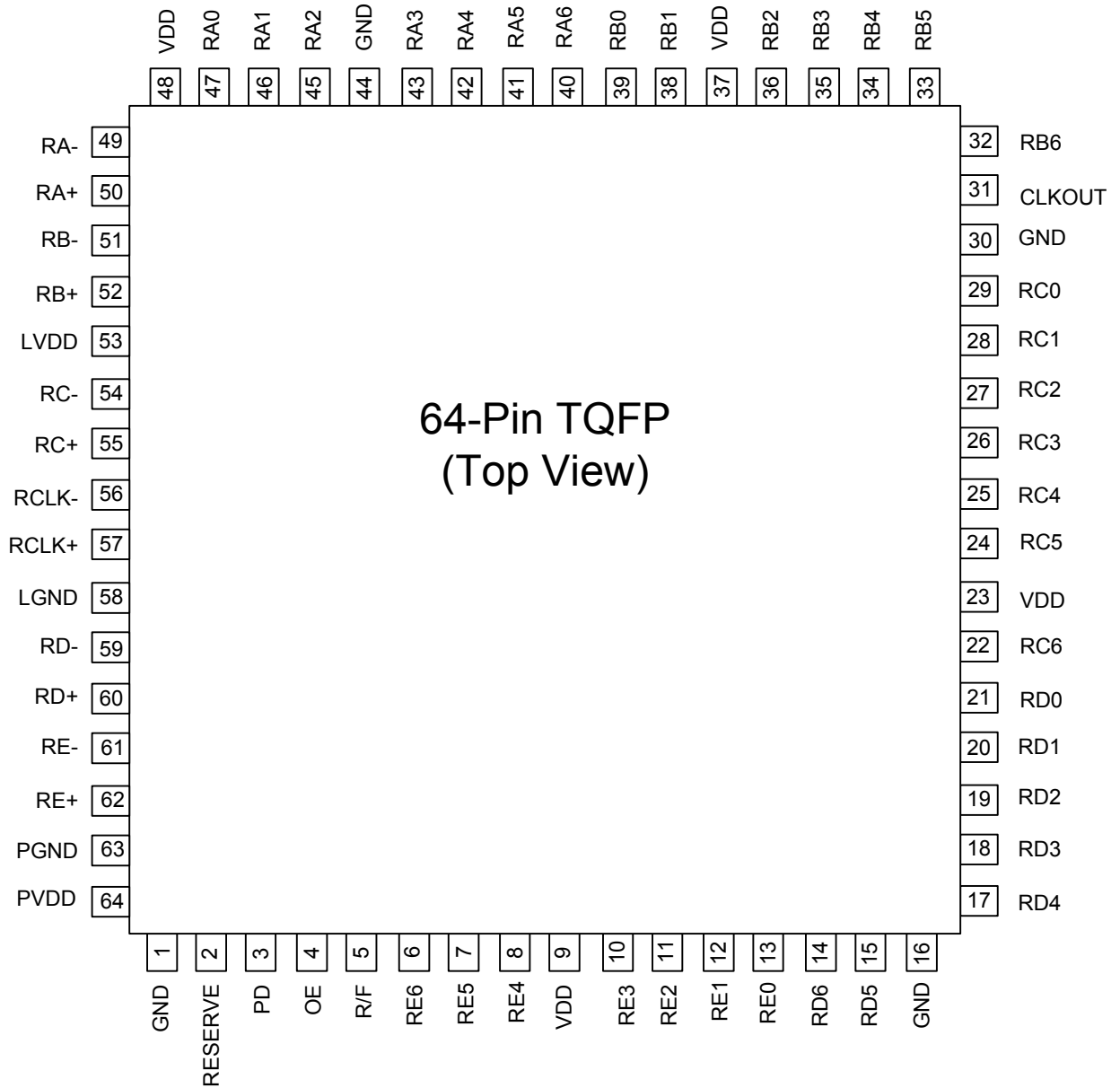


Figure 2. Pin Configuration (Top View)

## ●Pin Description

| Pin Name     | Pin No.                  | I/O        | Description  |
|--------------|--------------------------|------------|--|
| RA+, RA-     | 50,49                    | LVDS Input | LVDS data input<br>+ : Positive input of LVDS data differential pair.<br>- : Negative input of LVDS data differential pair.                          |
| RB+, RB-     | 52,51                    | LVDS Input |  |
| RC+, RC-     | 55,54                    | LVDS Input |  |
| RD+, RD-     | 60,59                    | LVDS Input |  |
| RE+, RE-     | 62,61                    | LVDS Input |  |
| RCLK+, RCLK- | 57,56                    | LVDS Input | LVDS clock Input   |
| RA6~RA0      | 40,41,42,43,<br>45,46,47 | Output     | LVCMOS data outputs.   |
| RB6~RB0      | 32,33,34,35,<br>36,38,39 | Output     |  |
| RC6~RC0      | 22,24,25,26,<br>27,28,29 | Output     |  |
| RD6~RD0      | 14,15,17,18,<br>19,20,21 | Output     |  |
| RE6~RE0      | 6,7,8,10,<br>11,12,13    | Output     |  |
| RESERVE      | 2                        | Input      | Reserved input must be "Low" for normal operation.   |
| PD           | 3                        | Input      | Power down input for the internal system.<br>H : Normal operation.<br>L : Power down (All output are "Low").   |
| OE           | 4                        | Input      | Power down input for the data output driver.<br>H : Output enable (Normal operation).<br>L : Output disable (All outputs are "Hi-Z").                |
| R/F          | 5                        | Input      | Select input pin for data output clock triggering edge.<br>H : Output data is latched on rising edge.<br>L : Output data is latched on falling edge. |
| VDD          | 9,23,37,48               | Power      | 3.3V output driver and digital core power supply pin.  |
| CLKOUT       | 31                       | Output     | LVCMOS level clock output.   |
| GND          | 1,16,30,44               | Ground     | Ground pin for both data output driver cells and the digital cores.  |
| LVDD         | 53                       | Power      | Power supply pin for LVDS core.  |
| LGND         | 58                       | Ground     | Ground pin for LVDS core.  |
| PVDD         | 64                       | Power      | Power supply pin for PLL core.   |
| PGND         | 63                       | Ground     | Ground pin for PLL core.   |

## ●Function Description

| PD | R/F | OE | Data output<br>(Rxn) <sup>(Note1)</sup> | Clock output                                     |
|----|-----|----|---|--|
| 0  | 0   | 0  | Hi-Z                                    | Hi-Z   |
| 0  | 0   | 1  | All fixed low                           | Fixed Low  |
| 0  | 1   | 0  | Hi-Z                                    | Hi-Z   |
| 0  | 1   | 1  | All fixed low                           | Fixed Low  |
| 1  | 0   | 0  | Hi-Z                                    | Hi-Z   |
| 1  | 0   | 1  | Data output                             | Output data is latched by falling edge of clock. |
| 1  | 1   | 0  | Hi-Z                                    | Hi-Z   |
| 1  | 1   | 1  | Data output                             | Output data is latched by rising edge of clock   |

(Note1): Rxn

x = A,B,C,D,E

n = 0,1,2,3,4,5,6

### ●Absolute Maximum Ratings

| Parameter                 | Symbol    | Ratings |              | Unit |
|---------------------------|-----------|---------|--------------|------|
|                           |           | Min     | Max          |      |
| Supply voltage            | $V_{DD}$  | -0.3    | +4.0         | V    |
| Input voltage             | $V_{IN}$  | -0.3    | $V_{DD}+0.3$ | V    |
| Output voltage            | $V_{OUT}$ | -0.3    | $V_{DD}+0.3$ | V    |
| Storage temperature range | Tstg      | -55     | +125         | °C   |

### ●Package power

| Package | PD(W)                  | DERATING(W/°C) <sup>(Note2)</sup> |
|---------|------------------------|-----------------------------------|
| TQFP64V | 0.7                    | 0.007                             |
|         | 1.0 <sup>(Note3)</sup> | 0.01 <sup>(Note3)</sup>           |

(Note2)At temperature  $T_a > 25^\circ\text{C}$

(Note3)Package power when mounting on the PCB board.

The size of PCB board :70 × 70 × 1.6(mm<sup>3</sup>)

The material of PCB board :The FR4 glass epoxy board.(3% or less copper foil area)

### ●Recommended Operating Conditions

| Parameter                   | Symbol    | Ratings |     |     | Unit | Condition                               |
|-----------------------------|-----------|---------|-----|-----|------|---|
|                             |           | Min     | Typ | Max |      |   |
| Supply voltage              | $V_{DD}$  | 2.3     | 3.3 | 3.6 | V    | VDD, LVDD, PVDD                         |
| Supply Noise Voltage        | $V_{NOZ}$ | -       | -   | 0.1 | V    |   |
| Operating temperature range | $T_{opr}$ | -40     | -   | +85 | °C   | Clock frequency from 8MHz up to 90MHz   |
|                             |           | 0       | -   | +70 | °C   | Clock frequency from 90MHz up to 112MHz |

### •DC characteristics

Table 1. LVCMOS DC Specifications (VDD=2.3~3.6V, Ta=-40~+85°C)

| Parameter                 | Symbol           | Limits                |     |                       | Unit | Conditions  |
|---------------------------|------------------|-----------------------|-----|-----------------------|------|---|
|                           |                  | Min                   | Typ | Max                   |      |   |
| High Level Input Voltage  | V <sub>IH</sub>  | V <sub>DD</sub> × 0.8 | -   | V <sub>DD</sub>       | V    |   |
| Low Level Input Voltage   | V <sub>IL</sub>  | 0.0                   | -   | V <sub>DD</sub> × 0.2 | V    |   |
| High Level Output Voltage | V <sub>OH</sub>  | V <sub>DD</sub> -0.5  | -   | V <sub>DD</sub>       | V    | I <sub>OH</sub> =-4mA (data)<br>I <sub>OH</sub> =-8mA (clock) |
| Low Level Output Voltage  | V <sub>OL</sub>  | 0.0                   | -   | 0.4                   | V    | I <sub>OL</sub> =4mA (data)<br>I <sub>OL</sub> =8mA (clock)   |
| Input Current             | I <sub>INC</sub> | -                     | -   | ± 10                  | μA   | 0V ≤ V <sub>IN</sub> ≤ V <sub>DD</sub>                        |

Table 2. LVDS Receiver DC Specifications (VDD=2.3~3.6V, Ta=-40~+85°C)

| Parameter                         | Symbol           | Limits |     |      | Unit | Conditions  |
|-----------------------------------|------------------|--------|-----|------|------|---|
|                                   |                  | Min    | Typ | Max  |      |   |
| Differential Input High threshold | V <sub>TH</sub>  | -      | -   | 100  | mV   | V <sub>OC</sub> =1.2V                               |
| Differential Input Low threshold  | V <sub>TL</sub>  | -100   | -   | -    | mV   | V <sub>OC</sub> =1.2V                               |
| Input Current                     | I <sub>INL</sub> | -      | -   | ± 25 | μA   | V <sub>IN</sub> =2.4V / 0V<br>V <sub>DD</sub> =3.6V |
| Common mode Voltage               | V <sub>OC</sub>  | 0.8    | 1.2 | 1.6  | V    | V <sub>ID</sub> =200mV                              |
| Differential Input Voltage        | V <sub>ID</sub>  | 100    | -   | 600  | mV   | -   |

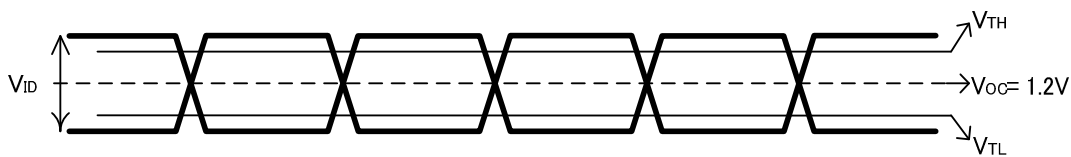


Figure 3. LVDS Receiver DC Specifications

•Supply Current

| Parameter                                    | Symbol     | Limits |     | Unit    | Conditions         |                        |
|--|------------|--------|-----|---------|--------------------|------------------------|
|  |            | Typ    | Max |         |                    |                        |
| Receiver supply current (Gray Scale Pattern) | $I_{RCCG}$ | 52     | -   | mA      | $f_{CLKOUT}=90MHz$ | $C_L=8pF, V_{DD}=3.3V$ |
| Receiver supply current (Worst Case Pattern) | $I_{RCCW}$ | 95     | -   | mA      | $f_{CLKOUT}=90MHz$ | $C_L=8pF, V_{DD}=3.3V$ |
| Receiver power down supply current           | $I_{RCCS}$ | -      | 10  | $\mu A$ | PD=L, OE=L         |                        |

Gray Scale Pattern

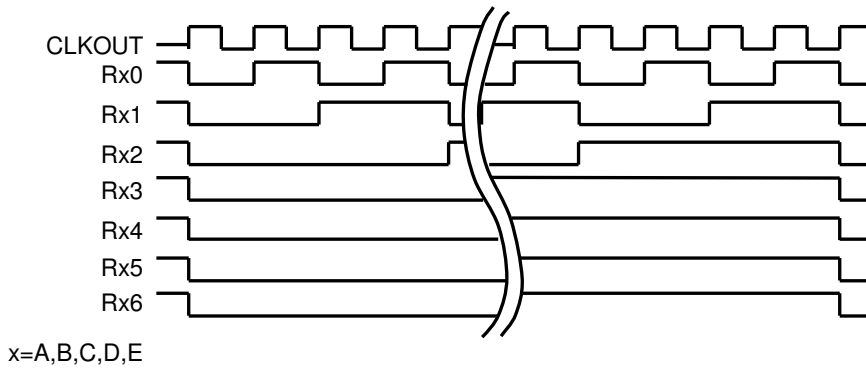


Figure 4. Gray Scale Pattern

Worst Case Pattern (Maximum power condition)

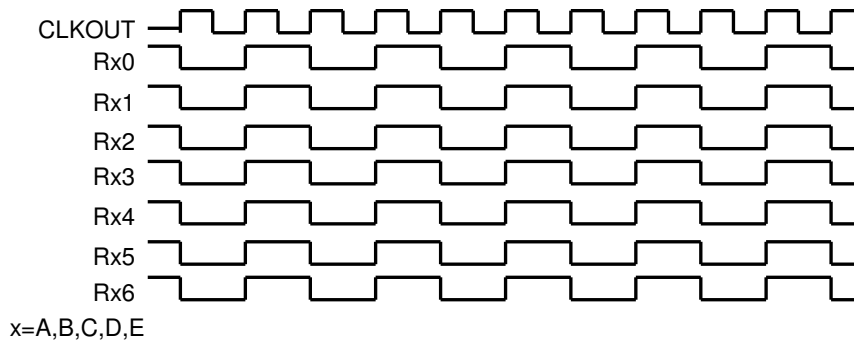


Figure 5. Worst Case Pattern



## ●AC characteristics

Table 3. Switching Characteristics (VDD=2.3~3.6V, Ta=-40~85°C)

| Parameter                     | Symbol            | Limits                        |                          |                               | Unit |
|-------------------------------|-------------------|-------------------------------|--------------------------|-------------------------------|------|
|                               |                   | Min                           | Typ                      | Max                           |      |
| CLKOUT Period                 | t <sub>RCP</sub>  | 8.93                          | -                        | 125                           | ns   |
| CLKOUT "H" Time               | t <sub>RCH</sub>  | -                             | 0.5t <sub>RCP</sub> -1.0 | -                             | ns   |
| CLKOUT "L" Time               | t <sub>RCL</sub>  | -                             | 0.5t <sub>RCP</sub> -1.0 | -                             | ns   |
| LVC MOS Data Setup to CLKOUT  | t <sub>RS</sub>   | 0.5t <sub>RCP</sub> -1.4      | -                        | -                             | ns   |
| LVC MOS Data Hold from CLKOUT | t <sub>RH</sub>   | 0.23t <sub>RCP</sub> -1.0     | -                        | -                             | ns   |
| LVC MOS Data Rise time        | t <sub>TLH</sub>  | -                             | 1.0                      | 2.0                           | ns   |
| LVC MOS Data Fall time        | t <sub>THL</sub>  | -                             | 1.0                      | 2.0                           | ns   |
| Input Data Position 0         | t <sub>RIP1</sub> | -0.25                         | 0.0                      | +0.25                         | ns   |
| Input Data Position 1         | t <sub>RIP0</sub> | $\frac{t_{RCIP}}{7} - 0.25$   | $\frac{t_{RCIP}}{7}$     | $\frac{t_{RCIP}}{7} + 0.25$   | ns   |
| Input Data Position 2         | t <sub>RIP6</sub> | $2 \frac{t_{RCIP}}{7} - 0.25$ | $2 \frac{t_{RCIP}}{7}$   | $2 \frac{t_{RCIP}}{7} + 0.25$ | ns   |
| Input Data Position 3         | t <sub>RIP5</sub> | $3 \frac{t_{RCIP}}{7} - 0.25$ | $3 \frac{t_{RCIP}}{7}$   | $3 \frac{t_{RCIP}}{7} + 0.25$ | ns   |
| Input Data Position 4         | t <sub>RIP4</sub> | $4 \frac{t_{RCIP}}{7} - 0.25$ | $4 \frac{t_{RCIP}}{7}$   | $4 \frac{t_{RCIP}}{7} + 0.25$ | ns   |
| Input Data Position 5         | t <sub>RIP3</sub> | $5 \frac{t_{RCIP}}{7} - 0.25$ | $5 \frac{t_{RCIP}}{7}$   | $5 \frac{t_{RCIP}}{7} + 0.25$ | ns   |
| Input Data Position 6         | t <sub>RIP2</sub> | $6 \frac{t_{RCIP}}{7} - 0.25$ | $6 \frac{t_{RCIP}}{7}$   | $6 \frac{t_{RCIP}}{7} + 0.25$ | ns   |
| Phase Locked Loop Set Time    | t <sub>RPLL</sub> | -                             | -                        | 10.0                          | ms   |
| Clock Input Period            | t <sub>RCIP</sub> | 8.93                          | -                        | 125                           | ns   |

●AC Timing

■LVCMOS

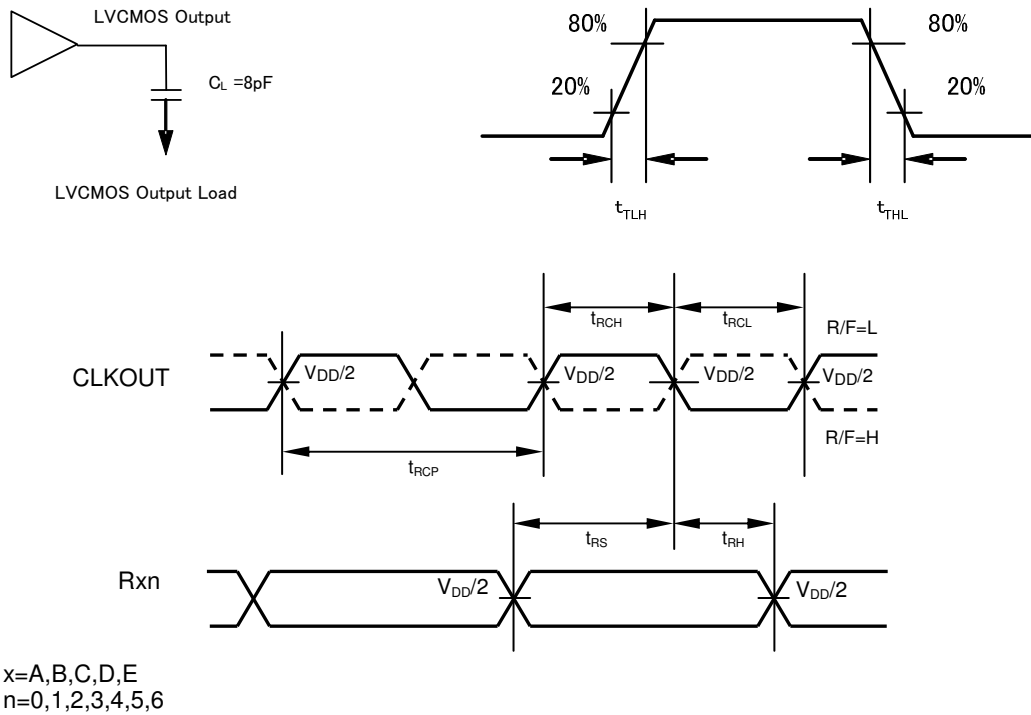


Figure 6. LVCMOS Output Timing

■Phase-Locked Loop Set Time

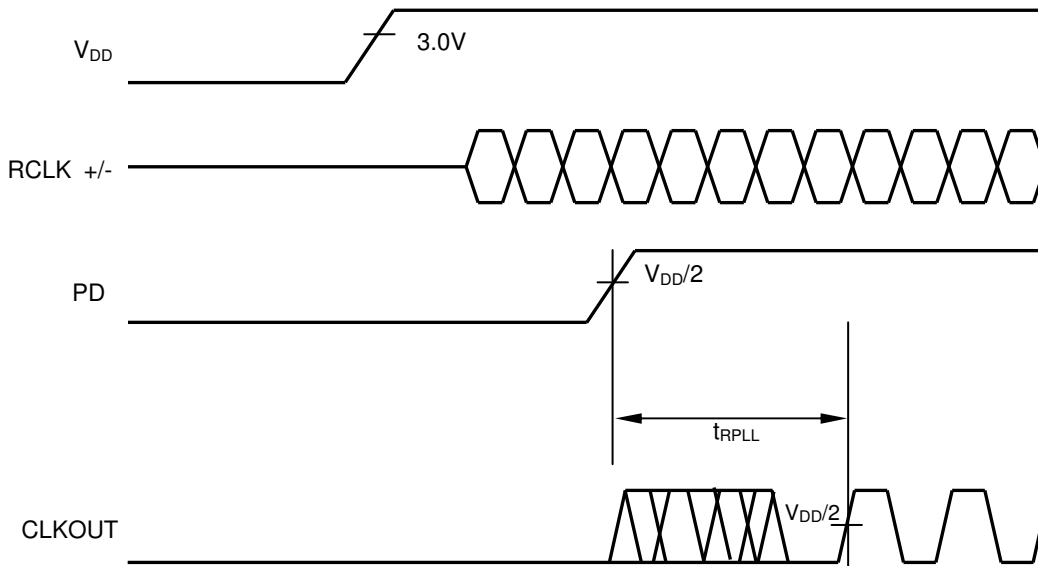


Figure 7. Phase-Locked Loop Set Time

•LVDS Data ,Clock Input Timing

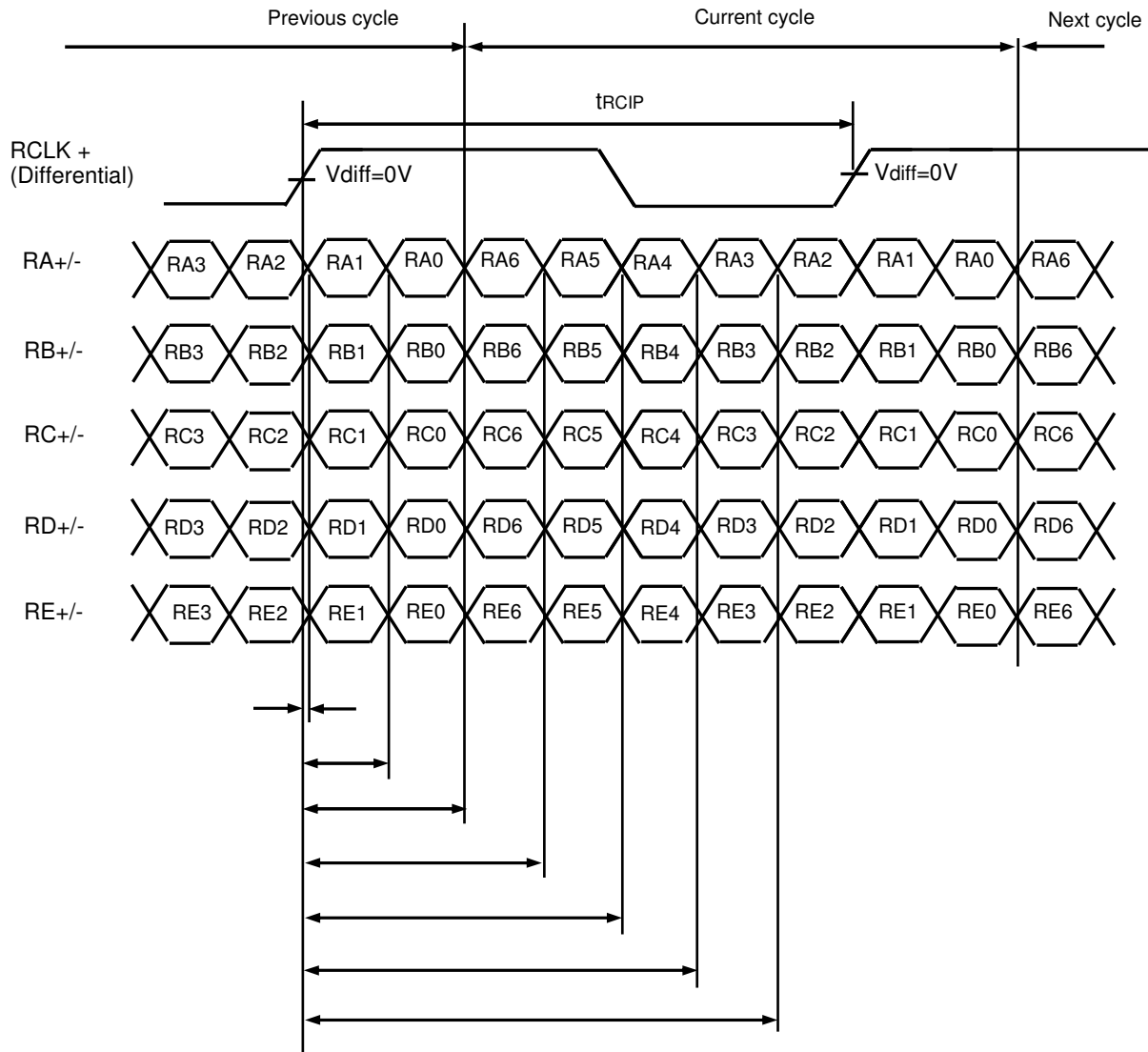


Figure 8. LVDS Data ,Clock Input Timing

•LVDS Data, Clock Input and LVCMOS Output Timing

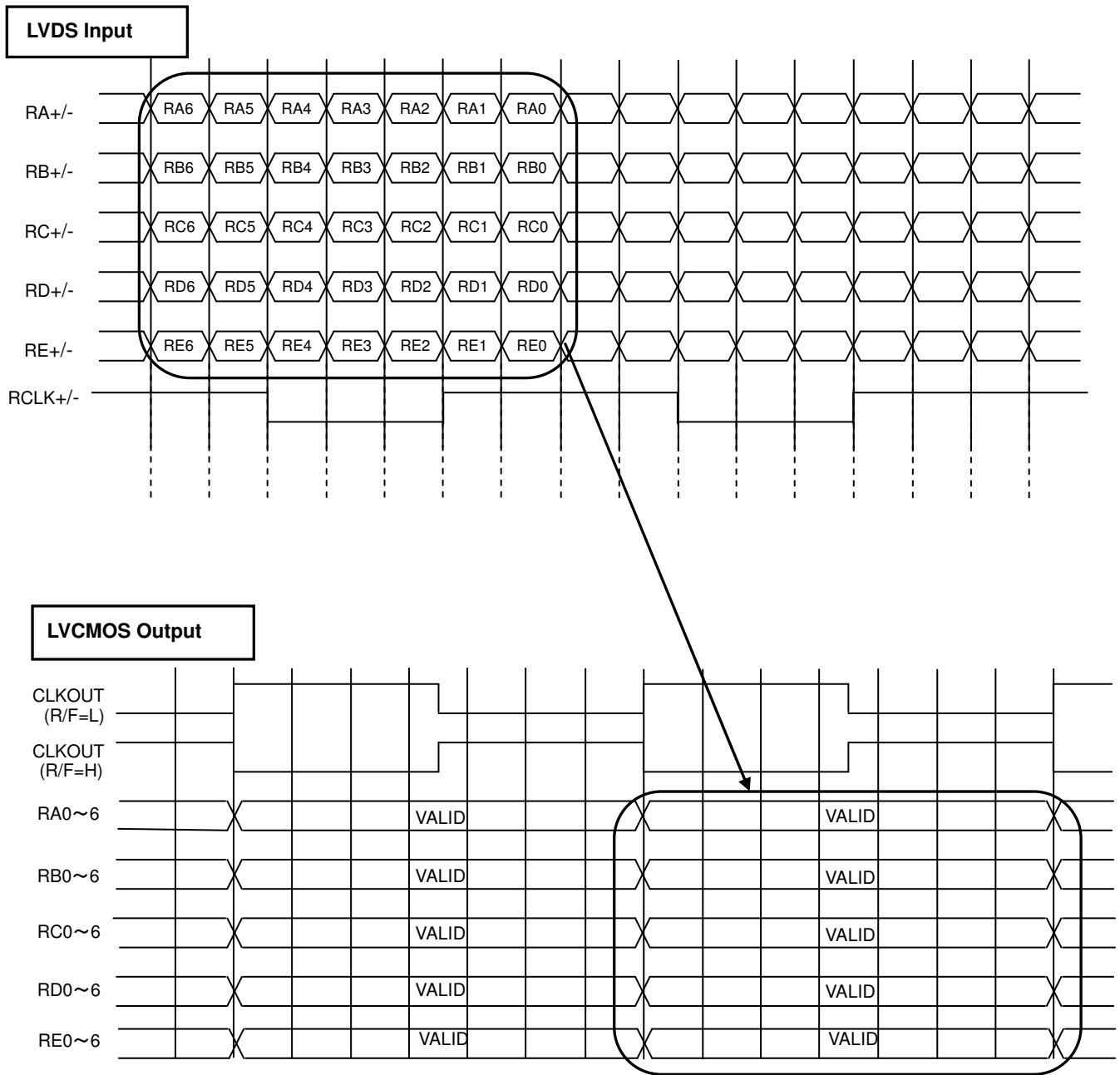


Figure 9. LVDS Data, Clock Input and LVCMOS Output Timing

●About the Power On Reset

Power on reset is not mandatory for this device.

(The PD pin should be set to high level when power on reset procedure is not used.)

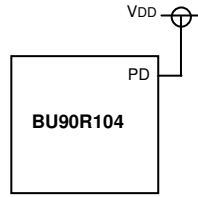
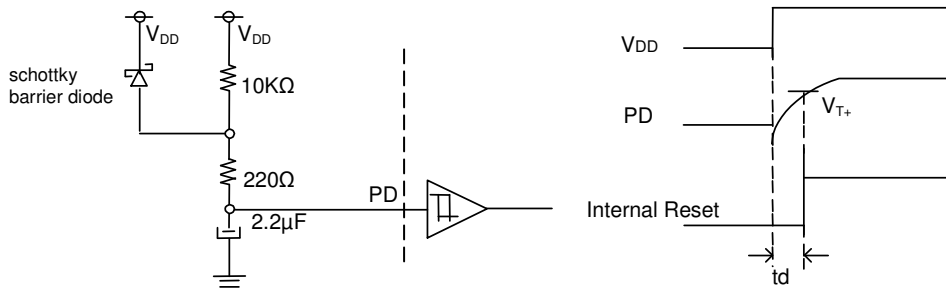


Figure 10. Terminal connection when power on reset is not used.

However, Power on reset procedure is strongly recommend for internal logic initialization by following two methods.

- ①The method of using CR circuit.
- ②The method of using external specific IC.

It is recommend to do enough examination for target application.



Be careful of temperature of the capacitor especially over and again. B characteristic ceramics and function polymer aluminum electrolysis are recommended.

$t_d$  is approximately equal to 20ms when the left RC coils are applied.

Figure 11. Power on reset by external a CR circuit

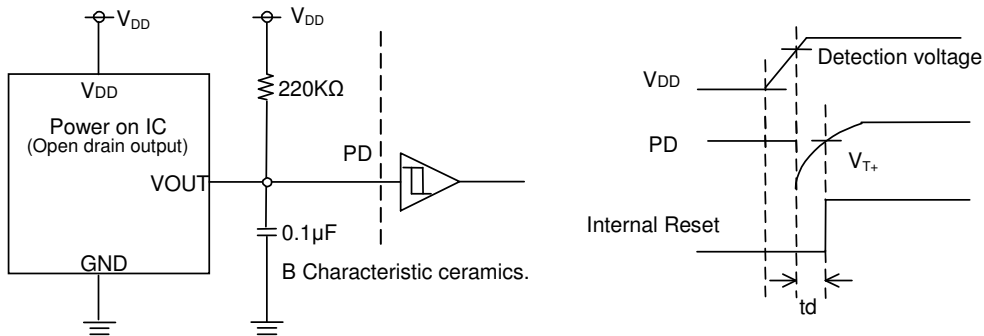
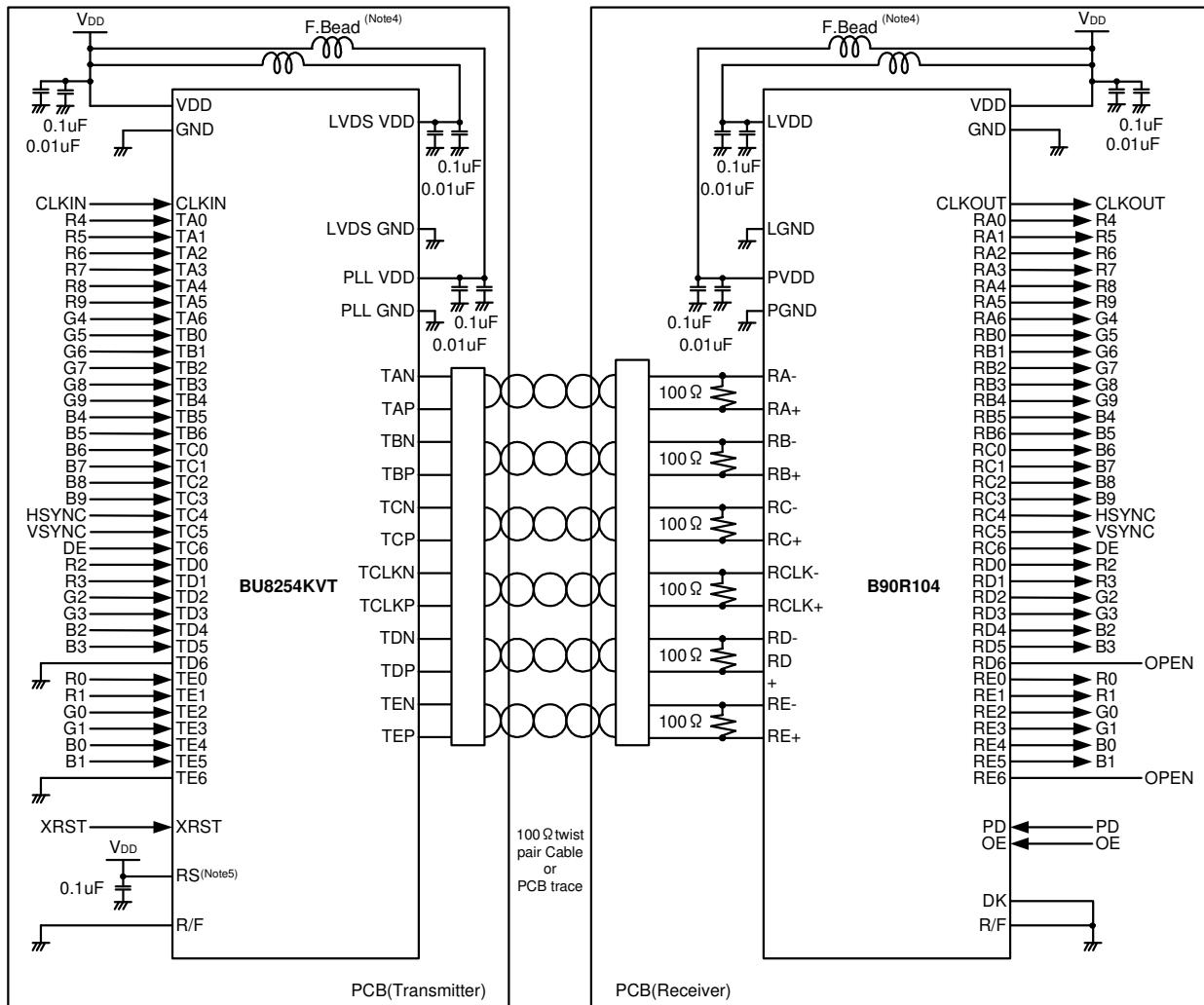


Figure 12. Power on reset by specific IC

●Application Circuit (10bit LVCMOS Level Input & LVCMOS Level Output)

Example:

- BU8254KVT : LVCMOS level input/Falling edge/LVDS normal(350mV) swing output
- BU90R104 : LVCMOS level output/Falling edge



(Note4) Recommended Parts:  
 F.Bead : BLM18A-Series (Murata Manufacturing Co.)  
 (Note5) If RS pin is tied to V<sub>DD</sub>, LVDS swing is 350 mV.  
 If RS pin is tied to GND, LVDS swing is 200 mV.

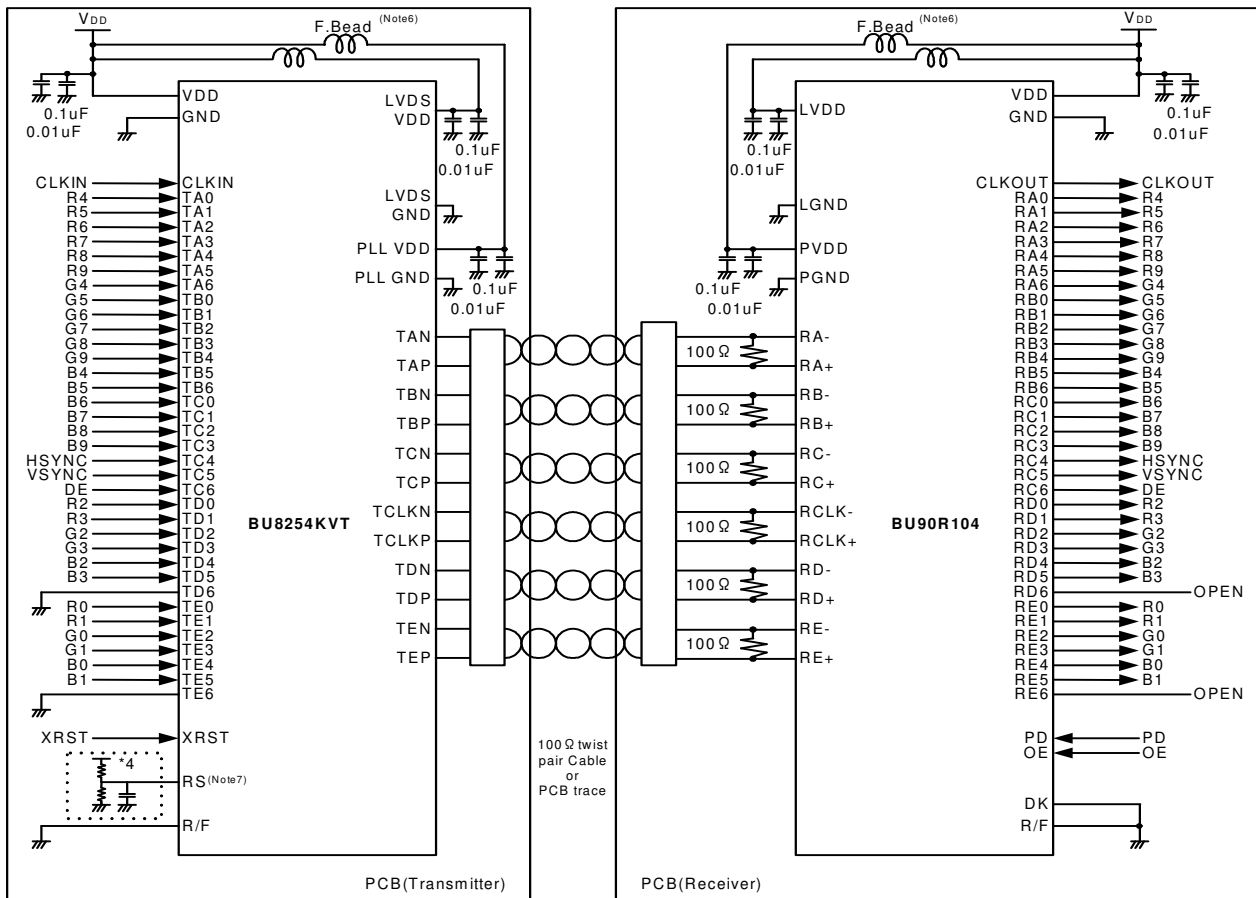
Figure 13. Application Circuit (10bit LVCMOS Level Input & LVCMOS Level Output)

●About the no used differential inputs  
 If there are no used differential inputs, be sure to set them into GND level.  
 The outputs are fixed High level, when differential inputs set GND.

●Application Circuit (10bit Small Swing Input & LVCMOS Level Output)

Example:

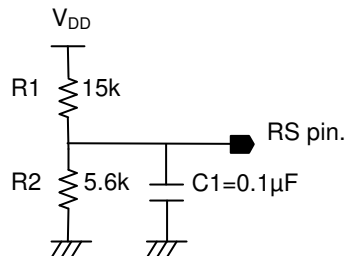
- BU8254KVT : LVCMOS level input/Falling edge/LVDS normal(350mV) swing output
- BU90R104 : LVCMOS level output/Falling edge



(Note6) Recommended Parts:

F.Bead : BLM18A-Series (Murata Manufacturing Co.)

(Note7) RS pin acts as VREF input pin when input voltage is set to half of high level signal input. We recommend to locate by-pass condenser near the RS pin.



Example for LVTTTL(1.8V input):(R1,R2)=(15kΩ,5.6kΩ)

Figure 14. Application Circuit (10bit Small Swing Input & LVCMOS Level Output)

●Status of this document

The Japanese version of this document is formal specification. A customer may use this translation version only for a reference to help reading the formal version.

If there are any differences in translation version of this document formal version takes priority

**●Notes for use**

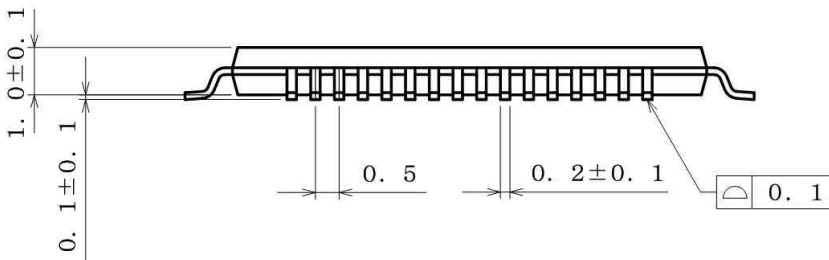
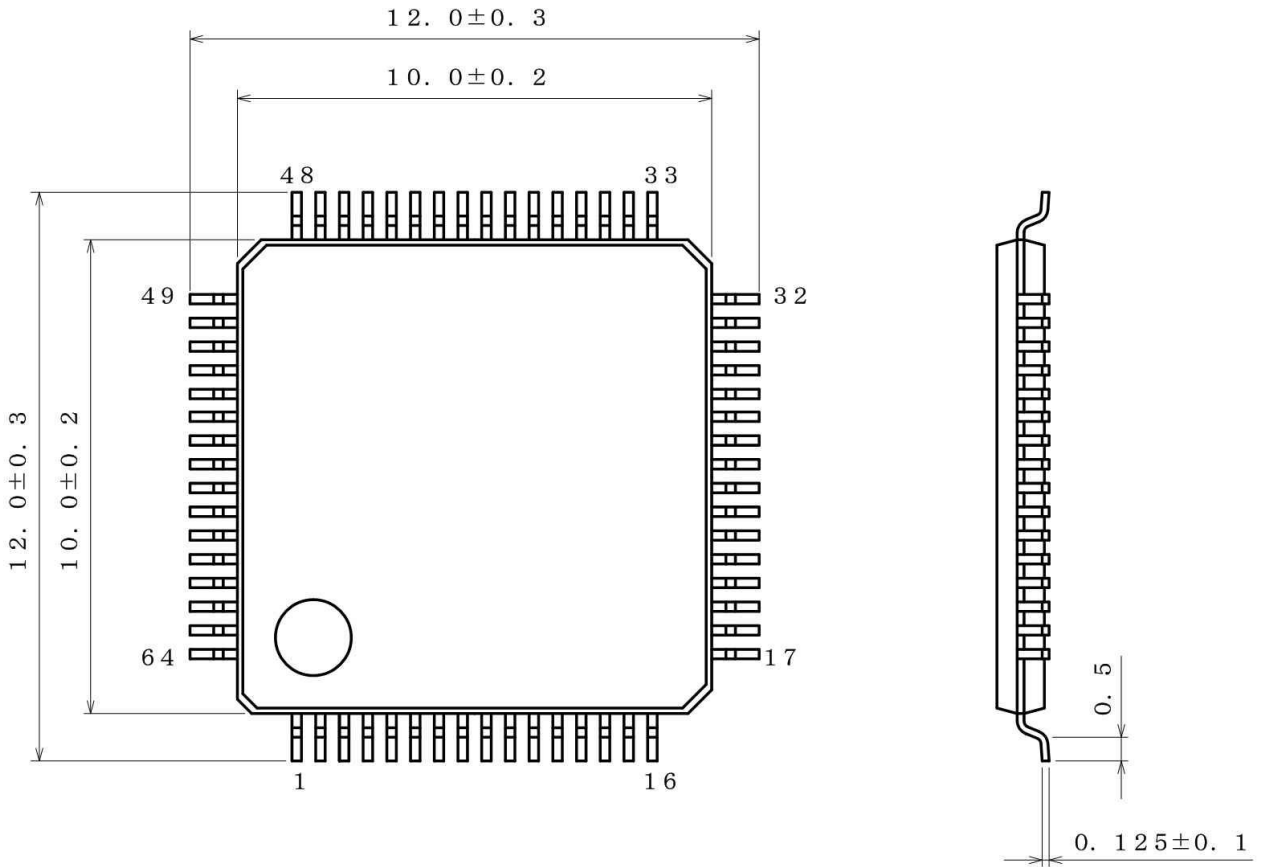
- 1) This chip is not designed to protect from radioactivity.
- 2) The chip is made strictly for the specific application or equipment.  
Then it is necessary that the unit is measured as need.
- 3) This document may be used as strategic technical data which subjects to COCOM regulations.





Physical Dimension, Tape and Reel Information

|              |         |
|--------------|---------|
| Package Name | TQFP64V |
|--------------|---------|



(UNIT : mm)  
 PKG : TQFP64V  
 Drawing No. B0722

<Tape and Reel information>

|                   |   |
|-------------------|---|
| Tape              | Embossed carrier tape (with dry pack)   |
| Quantity          | 1000pcs   |
| Direction of feed | E2<br>( The direction is the 1pin of product is at the upper left when you hold reel on the left hand and you pull out the tape on the right hand ) |

\*Order quantity needs to be multiple of the minimum quantity.

# Notice

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| JAPAN     | USA       | EU         | CHINA     |
|-----------|-----------|------------|-----------|
| CLASS III | CLASS III | CLASS II b | CLASS III |
| CLASS IV  |           | CLASS III  |           |

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  - Installation of redundant circuits to reduce the impact of single or multiple circuit failure
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  - Use of our Products in any types of liquid, including water, oils, chemicals, and organic solvents
  - Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
  - Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
  - Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
  - Sealing or coating our Products with resin or other coating materials
  - Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - Use of the Products in places subject to dew condensation
- The Products are not subject to radiation-proof design.
- Please verify and confirm characteristics of the final or mounted products in using the Products.
- In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- De-rate Power Dissipation (Pd) depending on Ambient temperature (Ta). When used in sealed area, confirm the actual ambient temperature.
- Confirm that operation temperature is within the specified range described in the product specification.
- ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

## Precaution for Mounting / Circuit board design

- When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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### Precaution for Electrostatic

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of Ionizer, friction prevention and temperature / humidity control).

### Precaution for Storage / Transportation

1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
  - [a] the Products are exposed to sea winds or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

### Precaution for Product Label

QR code printed on ROHM Products label is for ROHM's internal use only.

### Precaution for Disposition

When disposing Products please dispose them properly using an authorized industry waste company.

### Precaution for Foreign Exchange and Foreign Trade act

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